

DATA SHEET

GENERAL PURPOSE CHIP RESISTORS RC2010 (Pb Free) 5%, 1%



Product specification – Sep 16, 2004 V.2



Phicomp

SCOPE

This specification describes RC2010 series chip resistors with lead-free terminations made by thick film process.

ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

PHYCOMP ORDERING CODE

XXX XXXXX L

I2NC CODE 2322

(1)		(2) (3) (4)			
		START			EMBOSSED TAPE ON REEL (units) (2)
	2010	IN ⁽¹⁾	(%)	RANGE	4,000
	PRCIII	2322	±5%	I to 22 $M\Omega$	760 60xxx
	PRCIII	2322	±1%	I to $10M\Omega$	761 6xxxx
	Jumper	2322	-	0 Ω	760 90003

- (1) The resistors have a 12-digit ordering code starting with 2322.
- (2) The subsequent 4 or 5 digits indicate the resistor tolerance and packaging.
- (3) The remaining 4 or 3 digits represent the resistance value with the last digit indicating the multiplier as shown in the table of "Last digit of 12NC".
- (4) "L" means lead-free terminations.

ORDERING EXAMPLE

The ordering code of a PRCIII resistor, value 56 Ω with ±1% tolerance, supplied in tape of 4,000 units per reel is: 232276165609L.

Last digit of 12N	С	
Resistance decade (3	3)	Last digit
0.01 to 0.0976 Ω		0
0.1 to 0.976 Ω		7
I to 9.76 Ω		8
10 to 97.6 Ω		9
100 to 976 Ω		1
I to 9.76 $k\Omega$		2
10 to $97.6~k\Omega$		3
100 to 976 $k\Omega$		4
I to 9.76 $M\Omega$		5
I0 to 97.6 MΩ		6
Example: 0.02 Ω	=	0200 or 200

0.3 Ω 3007 or 307 ΙΩ 1008 or 108 33 kΩ 3303 or 333 $10 M\Omega =$ 1006 or 106

CTC CODE

RC2010	<u>X</u>	<u>X</u>	<u>X</u>	\mathbf{XX}	XXXX	L
	(1)	(2)	(3)	(4)	(5)	(6)

(I) TOLERANCE				
F = ±1%				
J = ±5%				
(2) PACKAGING TYPE				

(3) TEMPERATURE COEFFICIENT OF RESISTANCE

K = Embossed taping reel

- = Base on spec

(4) TAPING REEL 07 = 7 inch dia, Reel

(5) RESISTANCE VALUE

5R6, 56R, 560R, 5K6, 56K, 22M.

(6) RESISTOR TERMINATIONS

L = Lead free terminations (pure Tin)

ORDERING EXAMPLE

The ordering code of a RC2010 $\,$ chip resistor, value 56 Ω with ±1% tolerance, supplied in 7-inch tape reel is: RC2010FK-0756RL.

NOTE

- 1. The "L" at the end of the code is only for ordering. On the reel label, the standard CTC or 12NC will be mentioned an additional stamp "LFP"= lead free production.
- 2. Products with lead in terminations fulfil the same requirements as mentioned in this datasheet.
- 3. Products with lead in terminations will be phased out in the coming months (before July 1st, 2006)



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MARKING

RC2010



E-24 series: 3 digits

First two digits for significant figure and 3rd digit for number of zeros



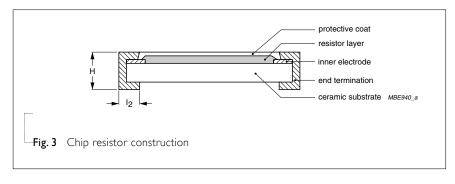
Both E-24 and E-96 series: 4 digits

First three digits for significant figure and 4th digit for number of zeros

For marking codes, please see EIA-marking code rules in data sheet "Chip resistors instruction".

CONSTRUCTION

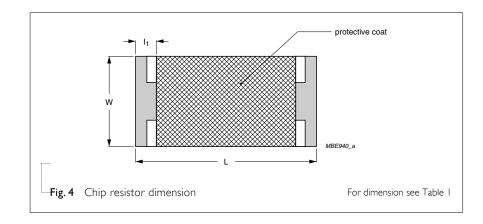
The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat and printed with the



resistance value. Finally, the two external terminations (pure Tin) are added. See fig. 3.

DIMENSIONS

Table I	
TYPE	RC2010
L (mm)	5.00 ±0.10
W (mm)	2.50 ±0.15
H (mm)	0.55 ±0.10
I _I (mm)	0.45 ±0.15
l ₂ (mm)	0.50 ±0.20



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ELECTRICAL CHARACTERISTICS

Table 2				
CHARACTERISTICS	F	RC2010 3/4 W		
Operating Temperature Range	- 55	_55 °C to +155 °C		
Maximum Working Voltage		200 V		
Maximum Overload Voltage		500 V		
Dielectric Withstanding Voltage		500 V		
	5% (E24)	I Ω to 22 M Ω		
Resistance Range	1% (E96)	I Ω to I0 $M\Omega$		
	Zero Ohm Ju	$_{\rm umper}$ < 0.05 Ω		
Temperature Coefficient	$10 \Omega < R \le 10 M\Omega$	±100 ppm/°C		
Temperature Coemcient	$R \le 10 \Omega$; $R > 10 M\Omega$	±200 ppm/°C		
Jumper Criteria	Rated Current	2.0 A		
jumper Criteria	Maximum Current	10.0 A		

<u>FOOTPRINT AND SOLDERING</u> PROFILES

For recommended footprint and soldering profiles, please see the special data sheet "Chip resistors mounting".

ENVIRONMENTAL DATA

For material declaration information (IMDS-data) of the products, please see the separated info "Environmental data".

PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style and packaging quantity

PRODUCT TYPE	PACKING STYLE	REEL DIMENSION	QUANTITY PER REEL
RC2010	Embossed taping reel (K)	7" (178 mm)	4,000 units

NOTE

1. For embossed tape and reel specification/dimensions, please see the special data sheet "Packing" document.

FUNCTIONAL DESCRIPTION

POWER RATING

RC2010 rated power at 70°C is 3/4 W

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

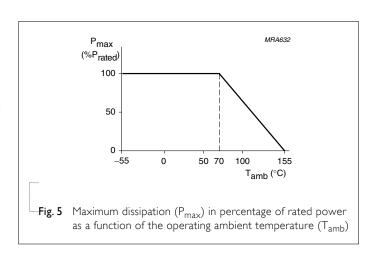
$$V=\sqrt{(P \times R)}$$

Where

V=Continuous rated DC or AC (rms) working voltage (V)

P=Rated power (W)

R=Resistance value (Ω)



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TESTS AND REQUIREMENTS

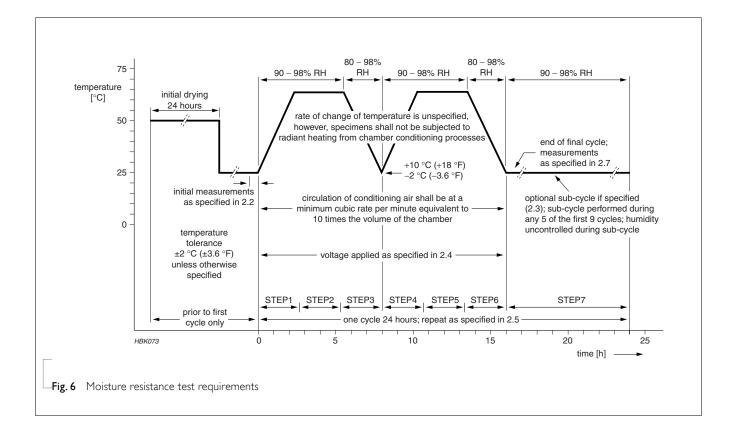
Table 4 Test condition, procedure and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS	
Temperature	MIL-STD-202F-method 304;	At +25/–55 °C and +25/+125 °C	Refer to table 2	
Coefficient of Resistance	JIS C 5202-4.8	Formula:		
(T.C.R.)				
		T.C.R= $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$		
		Where t_1 =+25 °C or specified room temperature		
		t_2 =-55 °C or +125 °C test temperature		
		R ₁ =resistance at reference temperature in ohms		
		R ₂ =resistance at test temperature in ohms		
Thermal Shock	MIL-STD-202F-method 107G;	At -65 (+0/-10) °C for 2 minutes and at +155	$\pm (0.5\% + 0.05~\Omega)$ for 1% tol.	
	IEC 60115-1 4.19	(+10/-0) °C for 2 minutes; 25 cycles	$\pm (1.0\% {+} 0.05~\Omega)$ for 5% tol.	
Low	MIL-R-55342D-Para 4.7.4	At -65 (+0/-5) °C for I hour, RCWV applied	$\pm (0.5\% + 0.05~\Omega)$ for 1% tol .	
Temperature		for 45 (+5/–0) minutes	$\pm (1.0\% + 0.05~\Omega)$ for 5% tol.	
Operation			No visible damage	
Short Time	MIL-R-55342D-Para 4.7.5;	2.5 × RCWV applied for 5 seconds at room	\pm (1.0%+0.05 Ω) for 1% tol.	
Overload	IEC 60115-1 4.13	temperature	$\pm (2.0\% + 0.05~\Omega)$ for 5% tol.	
			No visible damage	
Insulation	MIL-STD-202F-method 302;	RCOV for 1 minute	≥10 GΩ	
Resistance	IEC 60115-1 4.6.1.1	Type RC2010		
		Voltage (DC) 500 V		
Dielectric	MIL-STD-202F-method 301;	Maximum voltage (V _{rms}) applied for 1 minute	No breakdown or flashover	
Withstand	IEC 60115-1 4.6.1.1	Type RC2010		
Voltage		Voltage (AC) 500 V _{rms}		
		Total South		
Resistance to	MIL-STD-202F-method 210C;	Unmounted chips; 260 ±5 °C for 10 ±1	$\pm (0.5\% + 0.05~\Omega)$ for 1% tol.	
Soldering	IEC 60115-1 4.18	seconds	$\pm (1.0\% + 0.05~\Omega)$ for 5% tol.	
Heat			No visible damage	
Life	MIL-STD-202F-method 108A;	At 70±2 °C for 1,000 hours; RCWV applied for	$\pm (1\% + 0.05 \ \Omega)$ for 1% tol.	
	IEC 60115-1 4.25.1	1.5 hours on and 0.5 hour off	$\pm (3\% + 0.05 \ \Omega)$ for 5% tol.	

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ST	TEST METHOD	PROCEDURE	REQUIREMENTS	
Solderability	MIL-STD-202F-method 208A;	Solder bath at 245±3 °C	Well tinned (≥95% cove	ered)
	IEC 60115-1 4.17	Dipping time: 2±0.5 seconds	No visible damage	
Bending	JIS ⊂ 5202.6.14;	Resistors mounted on a 90 mm glass epoxy	\pm (1.0%+0.05 Ω) for 1%	6 tol.
Strength	IEC 60115-1 4.15	resin PCB (FR4)	\pm (1.0%+0.05 Ω) for 5%	á tol.
		Bending: 2 mm	No visible damage	
Resistance to	MIL-STD-202F-method 215;	Isopropylalcohol (C ₃ H ₇ OH) or dichloromethane	promethane No smeared	
Solvent	IEC 60115-1 4.29	(CH ₂ Cl ₂) followed by brushing		
Noise	JIS C 5202 5.9;	Maximum voltage (V _{ms}) applied.	Resistors range	Value
	IEC 60115-1 4.12		R < 100 Ω	10 dB
			$100 \Omega \le R < 1 K\Omega$	24 dB
			$1 \text{ K}\Omega \leq R < 10 \text{ K}\Omega$	34 dB
			$10 \text{ K}\Omega \leq R < 100 \text{ K}\Omega$	44 dB
			$100 \text{ K}\Omega \leq R < 1 \text{ M}\Omega$	46 dB
			$1 \text{ M}\Omega \leq R \leq 22 \text{ M}\Omega$	48 dB
Humidity	JIS C 5202 7.5;	1,000 hours; 40±2 °C; 93(+2/–3)% RH	+/0.5%+0.05 (2) for 1%	4 tol
Humidity (steady state)	JIS C 5202 7.5; IEC 60115-8 4.24.8	I,000 hours; 40±2 °C; 93(+2/–3)% RH RCWV applied for I.5 hours on and 0.5 hour off	\pm (0.5%+0.05 Ω) for 1% \pm (2.0%+0.05 Ω) for 5%	
•	•	·	,	
(steady state)	IEC 60115-8 4.24.8	RCWV applied for 1.5 hours on and 0.5 hour off	$\pm (2.0\% + 0.05 \ \Omega)$ for 5%	
(steady state)	IEC 60115-8 4.24.8 EIA/IS 4.13B;	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260 ± 5 °C Dipping time: 30 ± 1 seconds	$\pm (2.0\% + 0.05 \ \Omega)$ for 5%	ś tol.
(steady state) Leaching	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260 ± 5 °C Dipping time: 30 ± 1 seconds	$\pm (2.0\% + 0.05 \ \Omega)$ for 5% No visible damage	ś tol.
(steady state) Leaching Intermittent	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260 ± 5 °C Dipping time: 30 ± 1 seconds At room temperature; $2.5 \times$ RCWV applied for 1 second on and 25 seconds off; total 10,000	$\pm (2.0\% + 0.05~\Omega)$ for 5% No visible damage $\pm (1.0\% + 0.05~\Omega)$ for 1%	ś tol.
Leaching Intermittent Overload Resistance to Vibration Moisture	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18 JIS C 5202 5.8	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles	$\pm (2.0\% + 0.05~\Omega)$ for 5% No visible damage $\pm (1.0\% + 0.05~\Omega)$ for 1%	6 tol. 6 tol. 6 tol.
Leaching Intermittent Overload Resistance to Vibration	IEC 60115-8 4.24.8 EIA/IS 4.13B; IEC 60115-8 4.18 JIS C 5202 5.8 On request	RCWV applied for 1.5 hours on and 0.5 hour off Solder bath at 260±5 °C Dipping time: 30±1 seconds At room temperature; 2.5 × RCWV applied for 1 second on and 25 seconds off; total 10,000 cycles On request	$\pm (2.0\% + 0.05~\Omega)$ for 5% No visible damage $\pm (1.0\% + 0.05~\Omega)$ for 1% $\pm (2.0\% + 0.05~\Omega)$ for 5%	6 tol. 6 tol. 6 tol.

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Product specification

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REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 2	Sep 16, 2004	-	- New datasheet for 2010 thick film 1% and 5% with lead-free terminations
			- Replace the 2010 part of pdf files: PRC111_1_5, PRC111_5_6
			- Test method and procedure updated